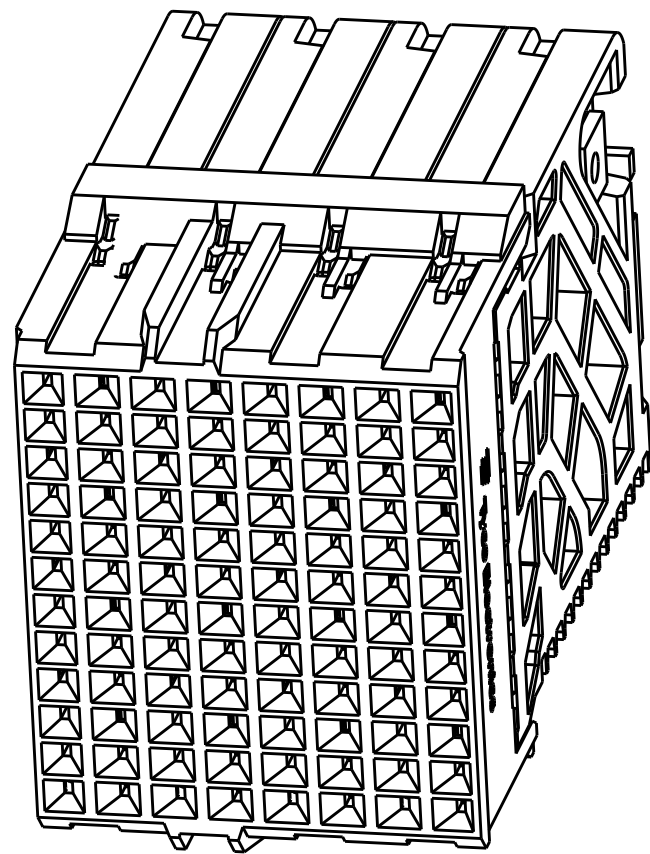


LOC	DIST	REVISIONS					
AD	00	P	LTR	DESCRIPTION	DATE	DWN	APVD
			B1	REVISED PER ECO-14-018036	11FEB2015	AP	DD

- 1 MATERIAL:
HOUSING: LCP, GLASS FILLED, UL94V-0.
TERMINALS: HIGH PERFORMANCE COPPER ALLOY.
- 2 FINISH:
30µ" SELECTIVE GOLD IN CONTACT AREA. SELECTIVE TIN
ON PCB TAILS, NICKEL OVERALL.

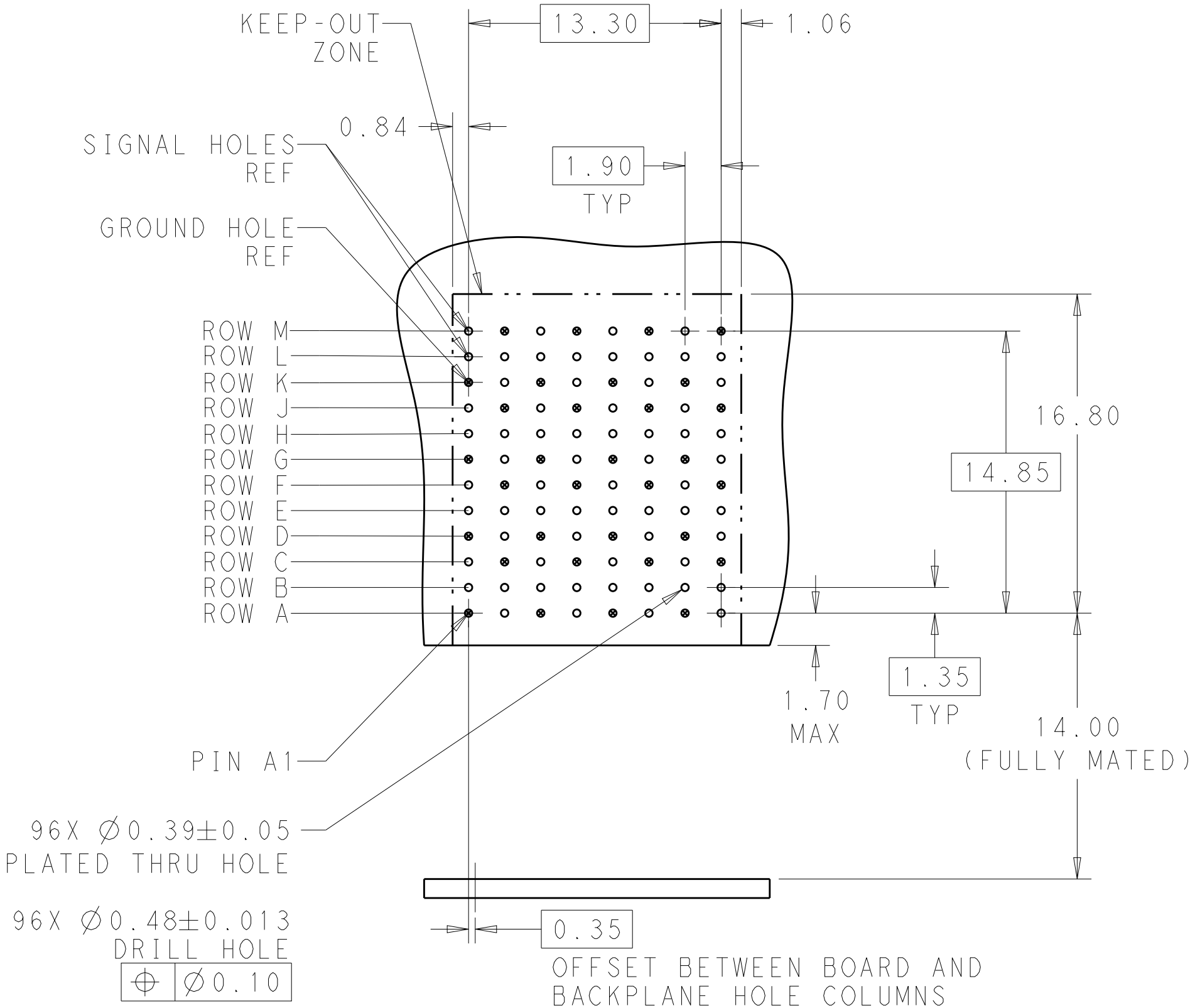
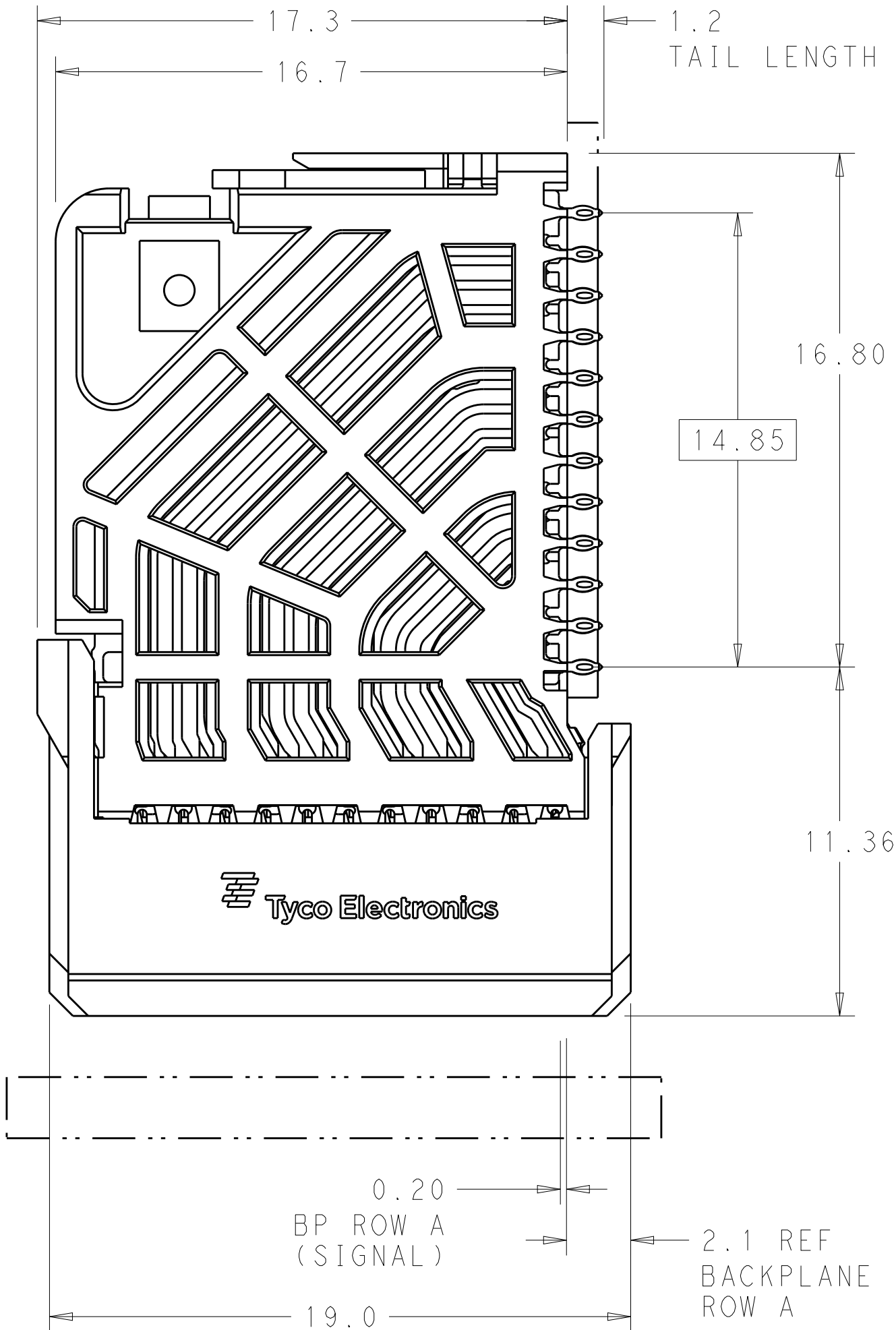
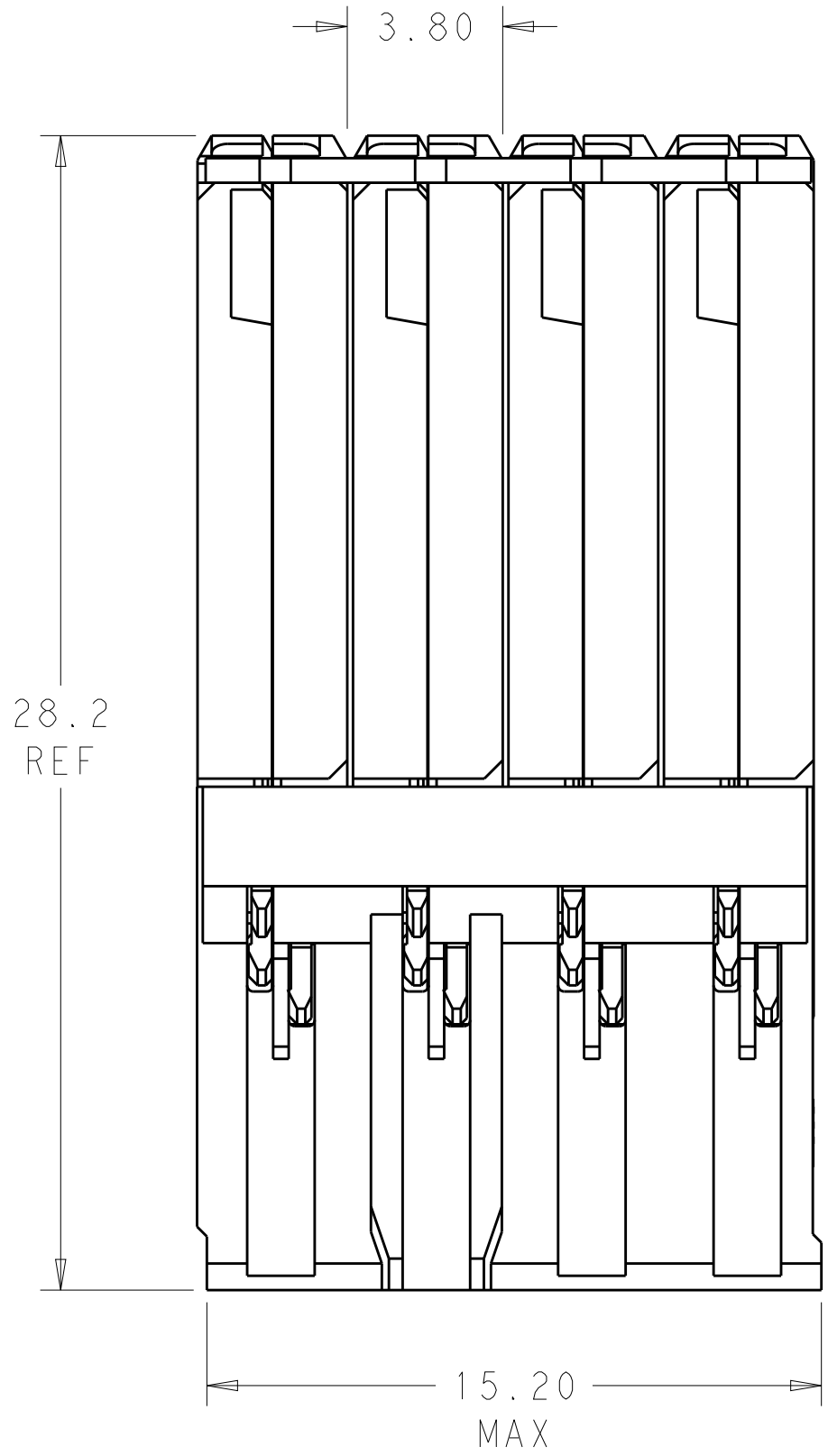


SCALE 4:1

REFER TO WWW.TE.COM
FOR PRODUCT AVAILABILITY

NONE	2	2057417-1
KEY POSITION	FINISH	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN 18MAY2011	 TE Connectivity		NAME	
		CHK D. DIXON 18MAY2011				
DIMENSIONS:		APVD D. DIXON 18MAY2011	PRODUCT SPEC		IMPACT, 4 PAIR, DAUGHTERCARD 8 COLUMN, UNGUIDED, SIGNAL MODULE, 0.39 EYELET	
mm			APPLICATION SPEC			
		0 P/LC ± 1 P/LC ±0.2 2 P/LC ±0.13 3 P/LC ± 4 P/LC ±	WEIGHT		SIZE CASE CODE DRAWING NO RESTRICTED TO A 100779C=2057417 -	
MATERIAL		FINISH	CUSTOMER DRAWING			
		SEE TABLE	SCALE 6:1		SHEET 1 OF 1 REV B1	



RECOMMENDED PCB LAYOUT
MIN BOARD THICKNESS 1.0